



32692
Customer Number

Patent
Case No.: 53434US009

AF/2827/

JPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.
Application No.: 09/690,600 Group Art Unit: 2827
Filed: October 17, 2000 Examiner: Luan C. Thai
Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED
SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

PETITION FOR EXTENSION OF TIME UNDER 37 CFR § 1.136(a)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

JUL 23 2004

Date

Kathleen M. Murray
Signed by: Kathleen M. Murray

Dear Sir:

Under the provisions of 37 CFR § 1.136(a), Applicants petition to extend the period for filing a reply in the above-identified application. The requested extension and appropriate fee are as follows (check time period desired):

☒ 37 CFR § 1.17(a)(1) - Extension within first month

Please charge any fees due, or credit any overpayment to Deposit Account No. 13-3723.

One copy of this sheet marked duplicate is also enclosed.

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Respectfully submitted,

23 July 2004
Date

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